DuPont Electronics & Imaging Interconnect Solutions Introduces New Metallization Offerings for High-Density Interconnect Applications in Printed Circuit Boards

Strategic Collaboration to Enable Next Generation Technology Platforms

WILMINGTON, Del. (PRWEB) May 12, 2020 -- DuPont Electronics & Imaging Interconnect Solutions (ICS), the leading integrated materials solution partner for advanced interconnects, today introduced new metallization offerings in advanced development stages for High-Density Interconnect (HDI) applications, a high-performance and fast-growing segment of the printed circuit board (PCB) industry. The offerings are part of the DuPont Electronics & Imaging ICS broad platform of products, where performance is optimized through product synergies and close partnership with customers.

The offerings include newly developed ionic palladium catalyst products for horizontal electroless copper systems, and a next generation via-fill electrolytic copper solution. These next-generation technologies are designed for fine-line HDI applications and deliver both high reliability and improved productivity. These qualities make them particularly suited to various application needs for smartphones, consumer electronics, telecom, and automotive.

“DuPont Electronics & Imaging ICS is committed to delivering a broad platform of integrated and advanced circuit materials to serve the PCB industry, and metallization products are part of it,” said Avi Avula, Vice President, General Manager, DuPont Electronics & Imaging. "We continue to invest in technology to bring new and advanced solutions to our customers, OEMs, and industry partners to drive innovation and enable next-generation product platforms that address the most challenging issues in the industry.”

DuPont Electronics & Imaging ICS metallization products have a long-standing reputation for excellent performance, consistent quality, and support from a strong, global R&D and technical service team with deep fundamental knowledge and know-how. Building upon these strengths, we are launching products in two areas:

- CIRCUPOSIT™ 6000 series - to address growing demand for ionic catalysts for horizontal electroless copper system. These products deliver high reliability and productivity regardless of application needs.
- MICROFILL™ EVF-III - electroplating solution for via-filling and through-hole plating in the fine-line HDI market, providing better surface uniformity, reduced scratch mark sensitivity, and wider operation latitude for a 20% productivity improvement at up to 20 ASF (Amperes per Square Foot).

Both product lines are currently available.

Photo can be downloaded at link: hi-resolution, low-resolution

Caption: DuPont Electronics & Imaging ICS introduced new metallization offerings in advanced development stages for High Density Interconnect (HDI) applications, a high performance and fast-growing segment of the printed circuit board (PCB) industry.

About DuPont Electronics & Imaging
DuPont Electronics & Imaging is a global supplier of materials and technologies serving the semiconductor,
advanced chip packaging, circuit board, electronic and industrial finishing, display, and digital and flexographic printing industries. From advanced technology centers worldwide, teams of talented research scientists and application experts work closely with customers, providing solutions, products and technical service to enable next-generation technologies. More information about DuPont Electronics & Imaging can be found on our [electronic solutions](https://www.dupont.com) and [image solutions](https://www.dupont.com) websites.

About DuPont
DuPont (NYSE: DD) is a global innovation leader with technology-based materials, ingredients and solutions that help transform industries and everyday life. Our employees apply diverse science and expertise to help customers advance their best ideas and deliver essential innovations in key markets including electronics, transportation, construction, water, health and wellness, food, and worker safety. More information can be found at [www.dupont.com](https://www.dupont.com).

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